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1. Name of conveying party(ies): Masatoshi Kanamaru 2-19-03

2. Name and address of receiving party(ies) Name: Hitachi, Ltd. Internal Address: \_\_\_\_\_

Additional name(s) of conveying party(ies) attached?  Yes  No.

3. Nature of conveyance:  Assignment  Merger  Security Agreement  Change of Name  Other: \_\_\_\_\_ Execution Date: November 12, 2002, November 22, 2002, November 12, 2002, November 11, 2002, and November 14, 2002

Street Address: 6, Kanda Surugadai 4-chome, Chiyoda City: Tokyo Country: Japan ZIP: \_\_\_\_\_ Additional name(s) and address(es) attached?  Yes  No

4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: \_\_\_\_\_ A. Patent Application No(s): 10/280,117 B. Patent No(s): \_\_\_\_\_ Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed: Name: Robert C. Colwell TOWNSEND AND TOWNSEND AND CREW LLP Two Embarcadero Center, 8th Floor San Francisco, California 94111-3834 (415) 576-0200

6. Total number of applications and patents involved 1 7. Total fee (37 CFR 3.41): -----\$40.00  Enclosed  Authorized to be charged to deposit account

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9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Robert C. Colwell Signature Date 2/10/03

Total number of pages including cover sheet, attachments and document 3

Mail documents to be recorded with required cover sheet information to: Commissioner of Patents and Trademarks, Box Assignments Washington, D.C. 20231

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PATENT REEL: 013775 FRAME: 0527

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# ASSIGNMENT ( 讓 渡 証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

"A SEMICONDUCTOR DEVICE AND A MANUFACTURING METHOD THEREOF"

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

- |     |                           |                     |
|-----|---------------------------|---------------------|
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| 7)  | _____                     | _____               |
| 8)  | _____                     | _____               |
| 9)  | _____                     | _____               |
| 10) | _____                     | _____               |